

OUR MOST SECURE WIRELESS SUBSYSTEM EVER



Laird Connectivity's 60 Series SOM brings all of Laird Connectivity's industry competence and capabilities into one solution. The SOM provides superior enterprise-class Wi-Fi connectivity with full support for 2x2 MIMO 802.11ac WLAN, plus Bluetooth 5.1 dual-mode. This solution is equipped with a Cortex A5 applications processor, wireless and wired connectivity, enterprise-grade security, LCD support, and comprehensive Linux board support package (BSP).

The 60 SOM is the ideal system on module for devices that require superior connectivity. Complete with the Sterling 60 series module and Summit Software Stack, the SOM provides superior wireless connectivity in harsh RF environments. It also supports dual-Ethernet and CAN bus for wired connectivity. The 30 mm x 30 mm form factor and variety of interfaces allow the 60 Series SOM to be used as a wireless bridge, main processing unit, or IoT gateway.

- **Improved Wi-Fi Performance** – 2x2 MIMO 802.11ac Wi-Fi supports greater throughput via support for additional spatial streams
- **Onboard cryptographic engine** which supports FIPS 140-2, meeting FIPS requirements with minimal performance impacts
- **Chain of Trust Architecture** – Laird Connectivity's Chain of Trust Architecture provides layers of security to mitigate attacks
- **CVE Checking and Penetration Testing** – Laird Connectivity monitors and patches for worldwide vulnerabilities and looks for new vulnerabilities and passes improvements via software releases
- **Reduced Time-to-Market** – Use the 60 Series SOM as the main processing unit for a fully-featured finished product
- **Fully Featured Development Kit** – Prototype and design with the full suite of 60 Series SOM features before integrating with your device

FEATURES AT A GLANCE



CONNECTIVITY AT THE CORE

The 60 Series SOM is designed with connectivity at the core; including Wi-Fi, Bluetooth, Dual-Ethernet, CAN bus, USB, UART, SPI, SD, I²C, and GPIOs.



SIGNED AND SECURED AT EVERY LAYER

Laird Connectivity's Chain of Trust Architecture creates secure modules, running approved software, with secured file systems.



THE FULL POWER OF THE SUMMIT SOFTWARE STACK

The stack provides superior performance in harsh environments, with faster channel scanning, 15x faster roaming, and 50% more consistent roaming when compared to other radios.



SOM AS A PLATFORM FOR FASTER TIME TO MARKET

The 60 Series SOM can serve as the main platform for your product, providing a feature rich base and speeding your design to market.



GLOBAL CERTIFICATIONS

Regulatory compliance for FCC, EU, and ISED Canada, as well as Wi-Fi Alliance certification and Bluetooth SIG Qualification.



INDUSTRY-LEADING SUPPORT

Laird Connectivity's Tier 2 and FAE support bring expert assistance to your integration, working with you and Laird Connectivity engineering to reduce your time to market.

APPLICATION AREAS



Healthcare and medical devices



IoT Bridging/Gateways



Industrial environments

Shared Specifications

Category	Feature	Specification
Chipset	Wireless Interface	NXP 88W8997/88PG823
Interfaces	Peripheral Interfaces	TFT LCD Display
		1x MMC/SD/SDIO Card Port
	2x SPI Master	
Bridging Interfaces	2x I ² C	ADC & GPIOs
		2x USB Host Ports
		1x CAN 2.0 bus
Antenna	1x 10/100 Ethernet (RMII)	1x 10/100/1000 Ethernet (RGMII)
		3x UART Lines
		1x USB Device Port
Networking	Wi-Fi	802.11ac, 2x2 MIMO w/Laird Connectivity's Summit Software Stack Adaptive Worldwide Mode
	Bluetooth	Bluetooth 2.1 EDR + 5.1 Bluetooth LE (Bluetooth 5 Ready)
	Ethernet	1x 10/100/100 w/ IEEE 1588 1x 10/100
Security	FIPS-140-2	Hardware accelerated via on-board hardware cryptographic engine
	Standards	WEP, WPA, WPA2-Personal, WPA2-Enterprise, WPA3-Personal, WPA3-Enterprise, and WPA3-Enterprise SuiteB 192-bit
	Encryption	WEP (RC4), TKIP (RC4), AES (Rijndael), Encryption Key Provisioning, Static, PSK
	Dynamic	802.1X Extensible Authentication Protocol Types (EAP-FAST, EAP-TLS, EAP-TTLS, PEAP-GTC, PEAP-MSCHAPv2, PEAP-TLS, LEAP)
Software	Development Tools	Precompiled SDK, toolchain, and development images Support to build your own image or SDK Host Communications API Eclipse Plugin
	Radio Management	Laird Connectivity Connection Manager, Web API, and touchscreen configuration via attached peripheral
Physical	Dimensions	30 mm x 30 mm x 2.8 mm (1.18 in. x 1.18 in. x 0.11 in.)
	Weight	5 g (.0011 lbs.)
Environmental	Operating Temperature	-30° to +85°C (-22° to +185°F)
Regulatory	Approvals	FCC/ISED/EU/MIC/KCC

For full specifications on the 60 Series SOM, please see the 60 SOM datasheet.

ORDERING INFORMATION

Part	Description
453-00003	60 Series SOM using 1 Gb LPDDR1 RAM and 2 Gb NAND flash
453-00004	60 Series SOM using 2 Gb LPDDR1 RAM and 4 Gb NAND flash
455-00003	Development Board for the 60 Series SOM using 1 Gb LPDDR1 RAM and 2 Gb NAND flash
455-00039	Development Board for the 60 Series SOM using 2 Gb LPDDR1 RAM and 4 Gb NAND flash
455-00004	LCD touchscreen for the 60 Series SOM development board (add-on)